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**Glass fibre woven cloth prodn. for laminated board - by
removing binder and treating with titanium cpd. for good workability by
punching and drilling**

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Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Main IPC	Week
JP 7069683	A	19950314	JP 93237192	A	19930831	C03C-025/00	199519 B

Priority Applications (No Type Date): JP 93237192 A 19930831

Patent Details:

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JP 7069683	A		4				

Abstract (Basic): JP 7069683 A

A woven cloth of glass fibres used for a laminated board is produced by removing binder or adhesive from a raw glass fibre woven cloth; and treating it with a titanium cpd. so as to lower the mechanical strength of glass fibres.

'WE-18W' (RTM, glass fibre woven cloth, Nittoboseki Corp.) was heated at 400 deg C for 20 hrs. to remove binder or adhesive. The cloth was immersed in a 1% cationic silane soln. dispersing 0.5% of titanium oxide powder with 0.3 micron average dia. After the soln. was squeezed, the cloth was dried.

USE/ADVANTAGE - For the prodn. of a glass fibre woven cloth which has a good workability for punching or drilling. Glass fibre woven cloth can be treated continuously. A Cu foil laminated circuit board using the new woven cloth has a good workability; the inside wall of a punched hole is quite flat.

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Derwent Class: A94; F03; L03; P73; V04; X12

International Patent Class (Main): C03C-025/00

International Patent Class (Additional): B32B-017/02; D03D-015/12;

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